GBU25005 THRU GBU2510

GLASS PASSIVATED SINGLE-PHASE BRIDGE RECTIFIER

REVERSE VOLTAGE: FORWARD CURRENT:

50 to 1000 VOLTS 25.0 AMPERE

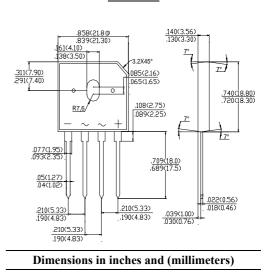


FEATURES

- · Glass passivated chip junction
- \cdot Reliable low cost construction utilizing molded
- plastic technique
- · Ideal for printed circuit board
- \cdot Low forward voltage drop
- · Low reverse leakage current
- \cdot High surge current capability

MECHANICAL DATA

Case: Molded plastic, GBU Epoxy: UL 94V-O rate flame retardant Terminals: Leads solderable per MIL-STD-202, method 208 guaranteed Mounting position: Any Weight: 0.23ounce, 6.6gram



GBU

Maximum Ratings and Electrical Characteristics

Ratings at 25 ambient temperature unless otherwise specified.

Single phase, half wave, $60H_Z$, resistive or inductive load.

For capacitive load, derate current by 20%.

	Symbols	GBU25005	GBU2501	GBU2502	GBU2504	GBU2506	GBU2508	GBU2510	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current with Heatsink at T _C =100	I _(AV)				25.0				Amp
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I _{FSM}	300							Amp
Maximum Forward Voltage Drop per Element at 12.5A DC and 25	V _F	1.05							Volts
Maximum Reverse Currentat $T_A=25$ at Rated DC Blocking Voltage $T_A=125$	I _R	10.0 500							uAmp
Typical Junction Capacitance (Note 1)	CJ	85							pF
Typical Thermal Resistance (Note 2)	$R_{\theta JC}$	0.6							/W
Operating and Storage Temperature Range	$T_{\rm J}$, Tstg			-	-55 to +15)			

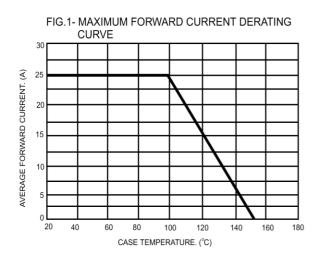
NOTES:

1- Measured at 1 MHz and applied reverse voltage of 4.0 VDC.

2- Thermal Resistance fromn Junction to Case with Device Mounted on 300mm x 300mm x 1.6mmCu Plate Heatsink.



RATINGS AND CHARACTERISTIC CURVES



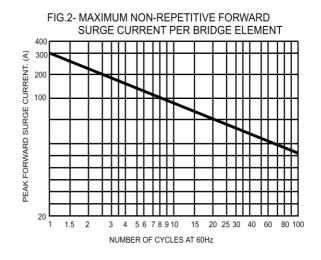


FIG.3- TYPICAL REVERSE CHARACTERISTICS PER BRIDGE ELEMENT

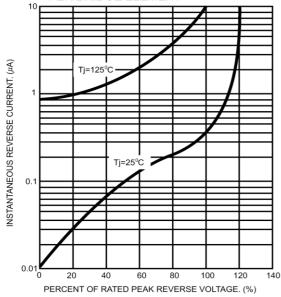
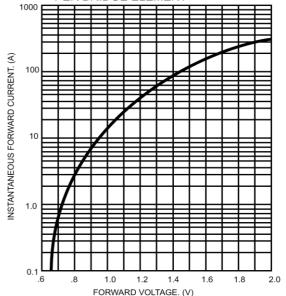


FIG.4- TYPICAL FORWARD CHARACTERISTICS PER BRIDGE ELEMENT



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